balance consisting of tin, wherein said alloy composition excludes bismuth.

4. (Twice Amended) A connection lead comprising:

a copper strip or other strip conductor; and

a plating provided on at least one side of the strip constructor, said plating being formed of a lead-free solder composed mainly of tin,

said plating containing 0.002 to 0.015% by mass of phosphorus with the balance consisting of tin and excluding bismuth, and having a shape such that the plating in a widthwise direction of the strip conductor has a bulge as viewed in section with an apex being located at a proper position in the widthwise direction of the strip conductor.

14. (Amended) The lead free solder according to claim 2, wherein:

the alloy composition further containing 2.0 to 5.0% by mass of silver and 0.01 to 2.0% by mass of copper.

15. (Amended) An alloy composition for a lead free solder used to connect a connection lead to a material, comprising:

0.002 to 0.015% by mass of phosphorus; and

tin, wherein said alloy composition excludes bismuth.

17. (Amended) An alloy composition for a lead free solder used to connect a connection lead to a material, consisting essentially of:

0.002 to 0.015% by mass of phosphorus;

2.0 to 5.0% by mass of silver;

0.01 to 2.0% by mass of copper; and

tin.

Please add the following new claims:

18. (New) The connection lead according to claim 4, wherein said plating further containing 2.0 to 5.0% by mass of silver and 0.01 to 2.0% by mass of copper.

19. (New) The alloy composition according to claim 15, further comprising:

2.0 to 5.0% by mass of silver; and

0.01 to 2.0% by mass of copper.